

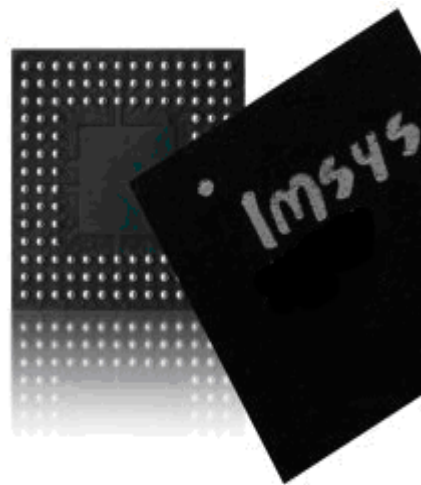


Hardware Reference

M20 Microcontroller Module

Revision 1.0

Copyright © Imsys Technologies AB



Imsys Technologies

Imsys Technologies AB, Sweden
Johanneslundsvägen 3
SE-194 61 Upplands Väsby
Sweden
+46 8 594 110 70 phone
+46 8 591 110 89 fax

Imsys Technologies, USA
9903 North Poetry Ln
Terrell, TX 75160
USA
+1 877 775 1627

838 Henderson Ave
Sunnyvale, CA 94086
USA

VAT:
556453-3247-01

Web:
www.imsystech.com

Copyright

Copyright © Imsys Technologies AB. All rights reserved. No part of this document may be reproduced or translated into any language by any means without the written permission of Imsys Technologies AB.

Disclaimer

Imsys Technologies AB makes no warranties for the contents of this document or the accuracy or completeness thereof and disclaims any implied warranties of merchantability or fitness for any particular purpose. Further, Imsys Technologies AB reserves the right to revise this document and to make changes without notifications to any person of such changes. The information contained in this document is provided solely for use in connection with Imsys Technologies AB products. This document should not be construed as transferring or granting a license to any intellectual property rights, neither expressed nor implied.

Imsys Technologies AB products have not been designed, tested, or manufactured for use in any application where failure, malfunction, or inaccuracy carries a risk of death, bodily injury, or damage to tangible property, including, but not limited to, use in factory control systems, medical devices or facilities, nuclear facilities, aircraft, watercraft or automobile navigation or communication, emergency systems, or other applications with a similar degree of potential hazard.

Revision History

Document: STO-DEV7022-CB	
Previous revision: -	
Section	Changes since last revision
	First release

Table of Contents

1.	About this document.....	4
2.	General description	4
2.1.	Key features	4
2.2.	Peripherals	4
2.3.	Block diagram.....	5
3.	Physical dimensions.....	5
3.1.	Dimensions	5
3.2.	Connector.....	6
4.	Pin list	6
4.1.	Pin descriptions	9
4.2.	Power supply.....	9
4.2.1.	3.3 V Supply.....	9
4.2.2.	1.8 V Supply.....	10
4.2.3.	RTC supply	10
4.2.4.	Analog ground.....	10
4.3.	IEEE1588	10
5.	Specifications	11
5.1.	Metrics.....	11
5.2.	DC Electrical Characteristics	11
5.3.	AC Electrical Characteristics	11
6.	Variants.....	12
	Appendix A. Schematics	13
	Appendix B. Bill of Materials.....	17

1. About this document

This document describes an IM3000-based microcontroller module offered to OEM customers for evaluation of Imsys platform for embedded control, for functional prototypes of customer products and development of application software, and for use in customer products.

The circuit board design described here can also be used as a starting point for optimized customer designs (schematics etc are available from Imsys).

The document mainly describes the pinout of the module connector and other physical aspects of the module. The operation of the IM3000-series microcontroller, as well as the specifications of the firmware platform, the tools, and the development system, are described elsewhere.

2. General description

The figures below show the M20 module in natural size.



Figure 1: Top side

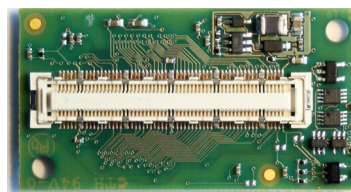


Figure 2: Bottom side

2.1. Key features

- IM3000-series microcontroller
- 8-32 MByte SDRAM memory
- 2-8 MByte flash memory
- Efficient switching power supply regulator
- Rugged FX10 connector
- RoHS compliant

2.2. Peripherals

The available peripheral interfaces vary with the specific member of the IM3000 series microcontroller with which the module is equipped, but can include:

- 2 Ethernet controllers, for direct connection to MII or RMII PHY's
- 3 asynchronous serial ports
- I2C, SPI, generic serial interface
- Dual DAC, and 8-channel ADC
- High-speed DMA-supported I/O bus, and generic 8-bit data interface

2.3. Block diagram

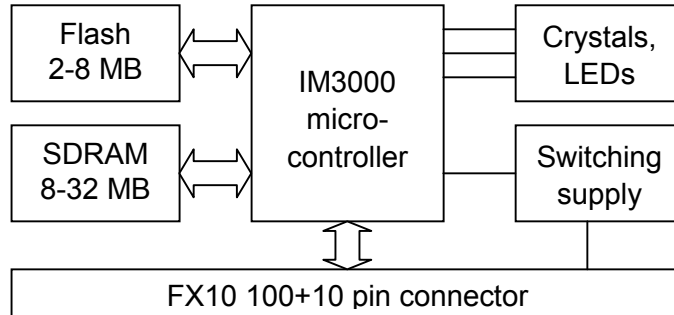


Figure 2: Block diagram

3. Physical dimensions

3.1. Dimensions

The module, when in place on the socket board, will be parallel to that. Its printed circuit board is 1.2 mm thick, and the distance between this and the socket board is either 4 or 5 mm, depending on the connector used on the socket board.

The design is specified to withstand very high shock acceleration, when the module is securely fastened using both mounting holes.

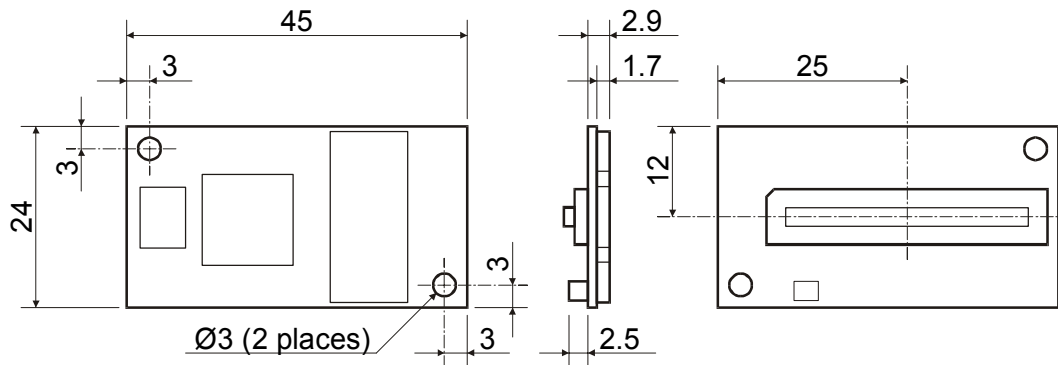


Figure 3: Dimensions (unit: mm)

3.2. Connector

The module connector is an FX10 receptacle, made by Hirose. It has 100 signal connections, plus 10 dedicated ground connections.

The figure below shows the pin numbering of the module connector. The chamfer at pin 1 is present also on the mating header connector, but it is solely a pin 1 marker and does not prevent insertion of the module the wrong way.

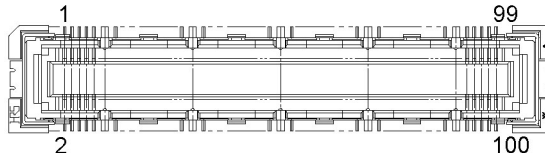


Figure 4: FX10 receptacle pin numbering

The 10 dedicated ground pins are not included in the pin numbering and do not appear in the pin list below. Nevertheless, all of the corresponding pins in the socket board must be connected to signal ground.

The mating connector on the socket board is a header, and can be any of the following types:

- FX10A-100P/10-SV or FX10B-100P/10-SV for 4 mm board-to-board distance
- FX10A-100P/10-SV1 or FX10B-100P/10-SV1 for 5 mm board-to-board distance

4. Pin list

The pins of the connector are listed roughly in the order from pin 1 through the odd numbered pins up to pin 99, then back along the other edge from pin 100 down to pin 2.

The order of pins within a few of the pin groups does not follow this ordering, where this would disrupt the logical sequence of pins. These pin groups are marked with **Note!** in the Pin # column.

The codes in the Type column are: I for Input, O for Output, B for Bidirectional, P for Power, (PU) for Pull Up, and (PD) for Pull Down.

Pin group	Pin #	Pin name	Type	Description
Misc.	1	RSTIN	I (PU)	Active low reset input
	3	MPLL_TSTO	O	PLL test / timestamp out
	5	MSDIN	I (PU)	Serial debug data in
	7	MCKOUT0	O	Debug clock
	9	MX1_CK	I	External clock input (1.8 V level)
	11	MCKOUT1	O	Programmable clock
	13	MSDOUT	O	Serial debug data out
	15	MIRQOUT	O	Active low debug interrupt

Pin group	Pin #	Pin name	Type	Description
GPIO / Generic Serial Interface	17	PD5_GSIIN	B	Port D bit 5 / GSI input
	19	PD6_GSIIO	B	Port D bit 6 / GSI bidirectional
	21	PD7_GSICK	B	Port D bit 7 / GSI clock
GPIO / I/O bus	23	PJ4_INEXT	B	Port J bit 4 / Active low I/O bus read strobe
	25	PJ5_ILDOUT	B	Port J bit 5 / Active low I/O bus write strobe
	27	PJ6_ILIOA	B	Port J bit 6 / Active low I/O bus address strobe
	29	PJ7_ICLK	B	Port J bit 7 / I/O bus clock
	31,33, 35,37, 39,41, 43,45	PI0_ID0 - PI7_ID7	B	Port I / I/O bus data
	47,49, 51,53, 55,57, 59,61	PH0_IDREQ0 - PH3_IDREQ3, PH4_IDACK0 - PH7_IDACK3	B	Port H / I/O bus DMA channels 0-3 control signals
	63,65, 67,69, 71,73, 75,77	PC0_IDREQ4 - PC4_IDREQ7, PC5_IDACK4 - PC7_IDACK7	B	Port C / I/O bus DMA channels 4-7 control signals
Supply	79	VCC18	P	Optional 1.8V power supply
Misc.	81	MRSTOUT	O	Active low reset output
	83	MWAKE	I (PD)	Active high wake-up input
	85,87	MIRQ0, MIRQ1	I (PU)	Active low interrupt signals
	89	MRXOUT	O	RTC test / Active high power supply wake-up output
GPIO / Async. serial ports	91,93, 95,97	PJ0_UTX1, PJ1_URX1, PJ2_URTS1, PJ3_UCTS1	B	Port J bits 0-3 / Serial port 1
	99, 100, 98,96	PE0_UTX2, PE1_URX2, PE2_URTS2, PE3_UCTS2	B	Port E bits 0-3 / Serial port 2
	88,92, 90,94 Note!	PE4_UTX3, PE5_URX3, PE6_URTS3, PE7_UCTS3	B	Port E bits 4-7 / Serial port 3
Misc.	86	WP	I (PD)	Active low flash write protect

Pin group	Pin #	Pin name	Type	Description
GPIO / Ethernet MII / Ethernet RMII	84,82,80,78,76,74,72,68 Note!	PF0_ETXEN, PF1_ETXCLK, PF2_ETXD0, PF3_ETXD1, PF4_ERXDV, PF5_ERXER, PF6_ERXD0, PF7_ERXD1	B	Port F / Ethernet MII / 1 st Ethernet RMII
	70,64,66,60,58,62,56,54 Note!	PG0_ETXER, PG1_ERXCLK, PG2_ETXD2, PG3_ETXD3, PG4_ECOL, PG5_ECRS, PG6_ERXD2, PG7_ERXD3	B	Port G / Ethernet MII / 2 nd Ethernet RMII
Supply	52	VBAT	P	3V battery backup for RTC
GPIO / Generic Parallel Interface	50,48,46,44,42,40,38,36	PB0_GPIO - PB7_GPI7	B	Port B / Generic Parallel Interface
Supply	34	GND_A	O	Analog ground reference output for ADC/DAC
	32	VREGEN	I	Active high enable for the on-board 1.8V linear regulator
	30,28	VCC33	P	Optional 3.3V power supply
Analog	26,24,22,20,18,16,14,12	ACH0 - ACH7	I	Analog to Digital Converter multiplexer inputs
	10,8	AOUT0, AOUT1	O	Digital to Analog Converter outputs
	6	EXTREF	I	Optional external voltage reference input for ADC
Supply	4	VRAWEN	I (PU)	Active high enable for the on-board 3.3V switch regulator
	2	VRAWIN	P	Optional unregulated 4.5-25V power supply

4.1. Pin descriptions

Almost all pins in the connector are directly connected to the IM3000 microcontroller, and to nothing else. Detailed descriptions of their functions can thus be found in the IM3000 Family Microcontrollers Data Book.

Exceptions to the above include supply related pins, which are dealt with in the next section, and the few signals listed below:

- MX1_CK: This pin is not connected to anything in most variants of the module, since the on-board crystal is normally used. If the module is equipped for external clocking, then the external clock shall be applied to this pin. The clock signal level must in that case be maximized to 1.8V.
- WP: This pin is connected to the write-protect pin of the on-board flash device. When pulled low or left open, the boot sector of the flash is write-protected. Typically only pulled high to do initial flash programming during manufacturing.
- ACH7: This analog input is biased to 0.9 V through 4.7 Mohm resistors to ground and the 1.8 V supply. Otherwise no difference compared to the other seven analog inputs.

4.2. Power supply

4.2.1. 3.3 V Supply

The module needs 3.3 V power for the on-board memory components and the microcontroller's I/O supply. This can be provided in two ways:

- Using the on-board switching regulator. In this case, unregulated 4.5 - 25 V is applied to VRAWIN, and VRAWEN is held high (1.8 - 25 V) or left open. Pulling VRAWEN low (below 0.4 V) will power down the module.

The excess current supply capability of the regulator is available at the VCC33 pins and can be used to power additional 3.3 V circuitry on the socket board.

- Using external regulated 3.3 V. If regulated 3.3 V is already available on the socket board, it can power the module through the VCC33 pins. In this case VRAWIN and VRAWEN are left unconnected.

This option can be used when the switching noise from the on-board regulator might otherwise cause EMC problems.

4.2.2. 1.8 V Supply

The module also needs 1.8 V power for the microcontroller's core supply. There are two alternatives for this as well:

- Using the on-chip linear regulator. If VREGEN is held high, the microcontroller's integrated linear regulator is used to provide 1.8 V.

The excess current supply capability of the regulator is available at the VCC18 pin and can be used to power additional 1.8 V circuitry on the socket board.

- Using external regulated 1.8V. If regulated 1.8 V is already available on the socket board, it can power the module through the VCC18 pin. In this case VREGEN shall be held low.

This option can be used to avoid the extra power dissipation of the linear regulator, if a more efficiently regulated 1.8 V supply is available.

4.2.3. RTC supply

The VBAT pin can be supplied from a lithium cell battery (typically 3.0 V) to provide power for the on-chip Real-Time Clock while other power supplies to the module are off.

If RTC operation during power-off is not necessary then VBAT can be left unconnected, the RTC is supplied from the main 3.3 V supply while that is powered.

4.2.4. Analog ground

The GNDA pin provides an analog ground reference to off-module circuitry connected to the analog interfaces (ADC/DAC).

If no such circuitry exists, then GNDA can be left unconnected.

4.3. IEEE1588

In some variants of the M20 module, there is support for the Precision Time Protocol according to the IEEE1588 standard. For this to be enabled, some connections must be present on the socket board.

- MPLL_TSTO (Ethernet timestamp output) must be connected to PC1_IDREQ5 (capture timer input)
- PC3_IDREQ7 (spike train output) must be connected to PB5_GPIO5 (interrupt capable input)

In addition, if the module is equipped for external clocking, that external clock (usually from a VCTCXO) must be connected to MX1_CK.

The spike train output can be used on the socket board to create a programmable pulse train signal by clocking a toggle-flipflop with it.

The above connections are already made on any socket board sold together with an IEEE1588-enabled module in a development kit.

5. Specifications

5.1. Metrics

Metric	Value
Dimensions	45 x 24 x 6.1 mm
Weight	5 g
Shock tolerance	200 G when screw-secured, 50 G otherwise
Operating temperature	0 – +70 °C
Storage temperature	-40 – +150 °C
MTBF	TBD

5.2. DC Electrical Characteristics

Parameter	Symbol	Min	Typ	Max
Switching 3.3 V regulator supply (when used)	V_{RAW}	4.5 V		25 V
Regulator efficiency ($V_{RAW} = 12$ V)	E_{RAW}		80 %	
3.3 V regulator output current ($V_{RAW} \geq 4.7$ V)	I_{33OUT}			400 mA
1.8 V linear regulator output current	I_{18OUT}			70 mA
I/O voltage supply	V_{IO}	2.97 V	3.3 V	3.63 V
Core voltage supply	V_{CORE}	1.62 V	1.8 V	1.98 V
RTC battery backup supply	V_{BAT}	2.7 V	3.0 V	3.63 V
I/O supply current ($V_{IO} = 3.3$ V, no I/O load, $f_{CORE} = 167$ MHz)	I_{IO}		TBD	TBD
Core supply current ($V_{CORE} = 1.8$ V, $f_{CORE} = 167$ MHz)	I_{CORE}		TBD	TBD
RTC backup current	I_{BAT}		TBD	
Input low voltage	V_{IL}			0.8 V
Input high voltage	V_{IH}	2.0 V		
Output low voltage ($ I_{OL} = \max$)	V_{OL}			0.4 V
Output high voltage ($ I_{OH} = \max$)	V_{OH}	2.4 V		
Output drive current (GPIO pins)	$ I_{OL} , I_{OH} $	2/8 mA		

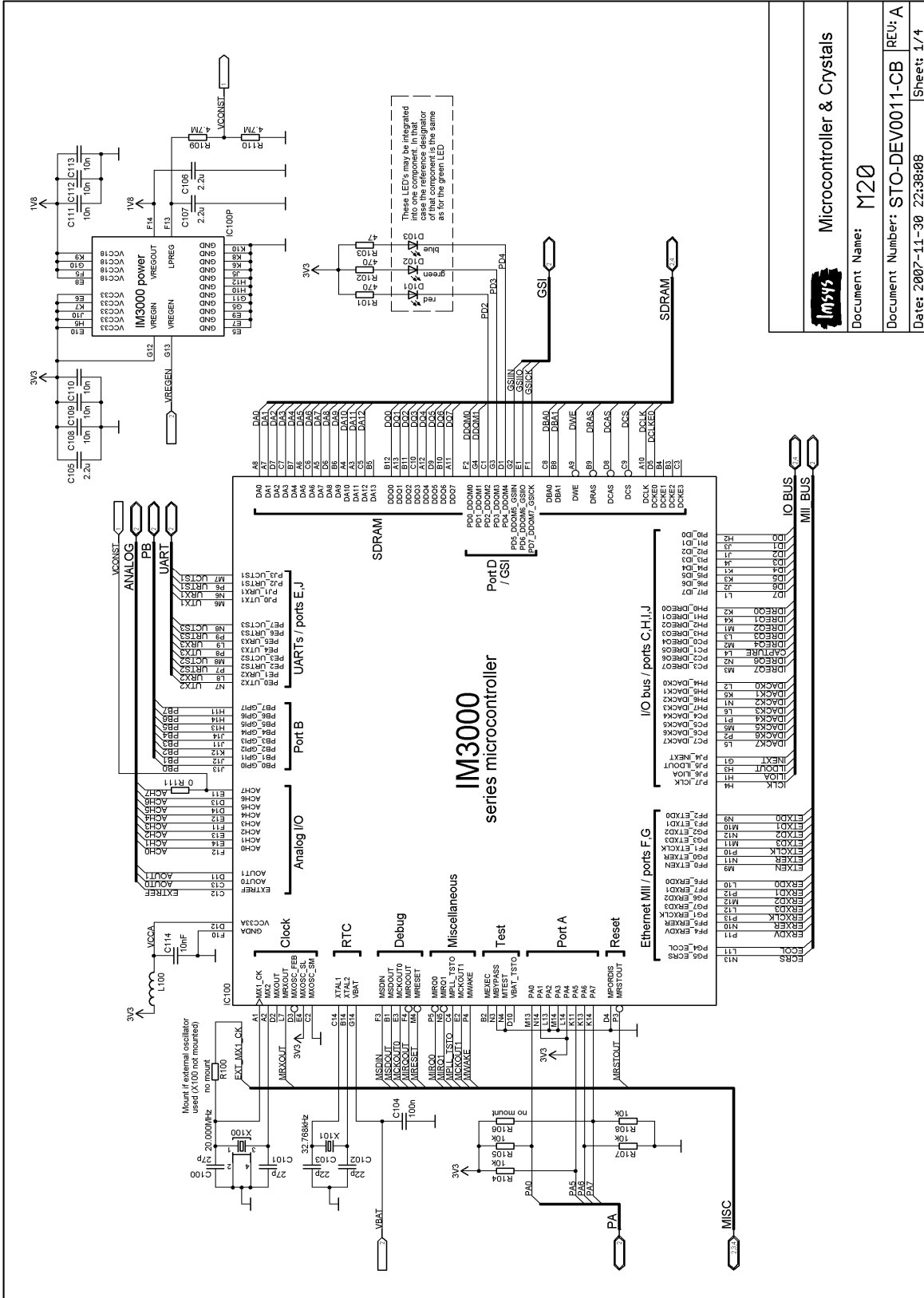
5.3. AC Electrical Characteristics

Parameter	Symbol	Min	Typ	Max
On-board main oscillator frequency	f_{OSC}		20 MHz	
On-board RTC oscillator frequency	f_{RTC}		32768 Hz	
Core & SDRAM frequency	f_{CORE}	20 MHz		167 MHz
External oscillator frequency on MX1_CK	f_{EXT}	5 MHz		41.7 MHz

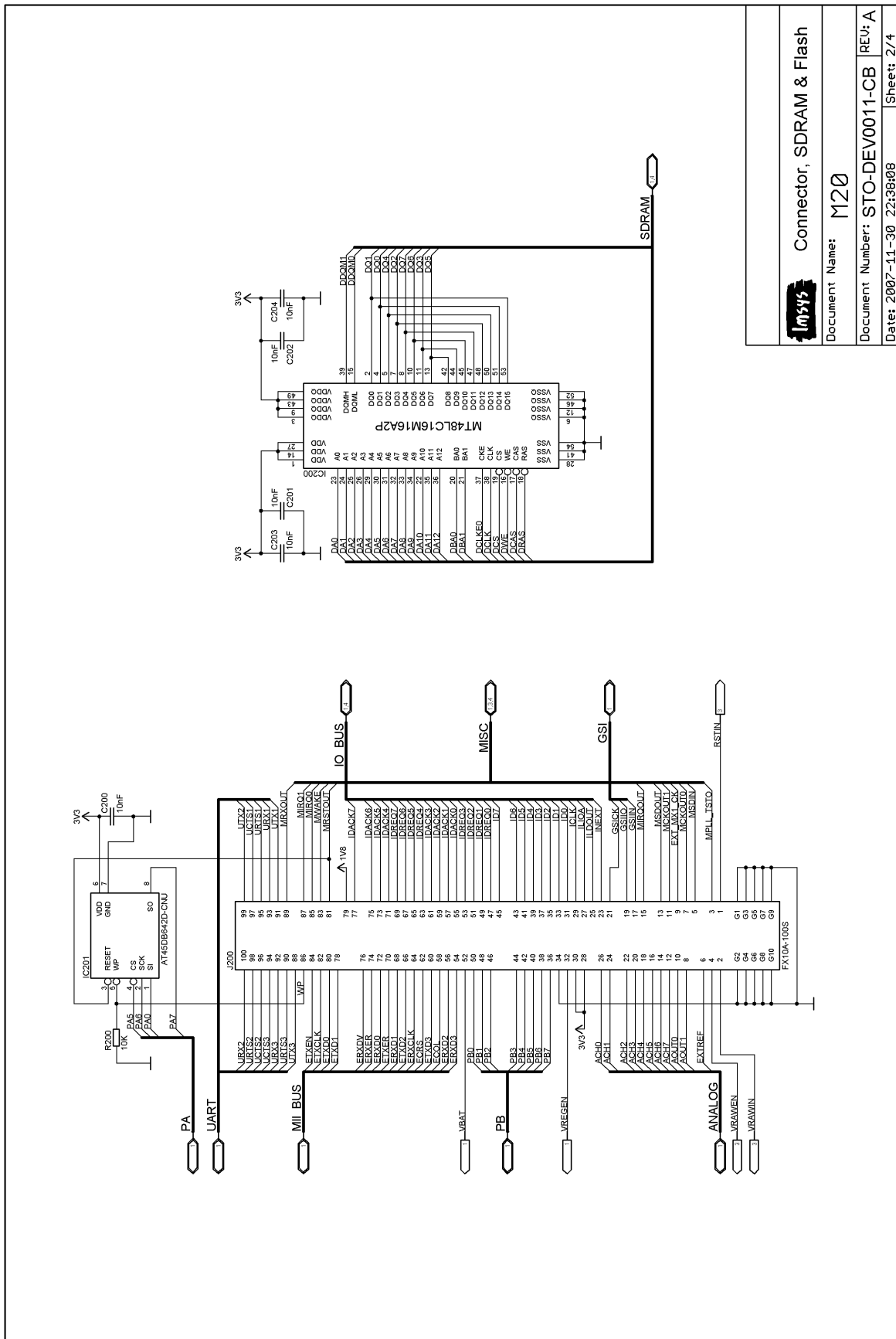
6. Variants

Variant	Clock	RAM	Flash	Notes
M210	167 MHz	32 MB	8 MB	Used on-board oscillator.

Appendix A. Schematics



Imsys Microcontroller & Crystals	
Document Name:	M20
Document Number:	STO-DEV0011-CB
Date:	2007-11-30
REV:	A
Sheet:	1/4



Imsys Connector, SDRAM & Flash

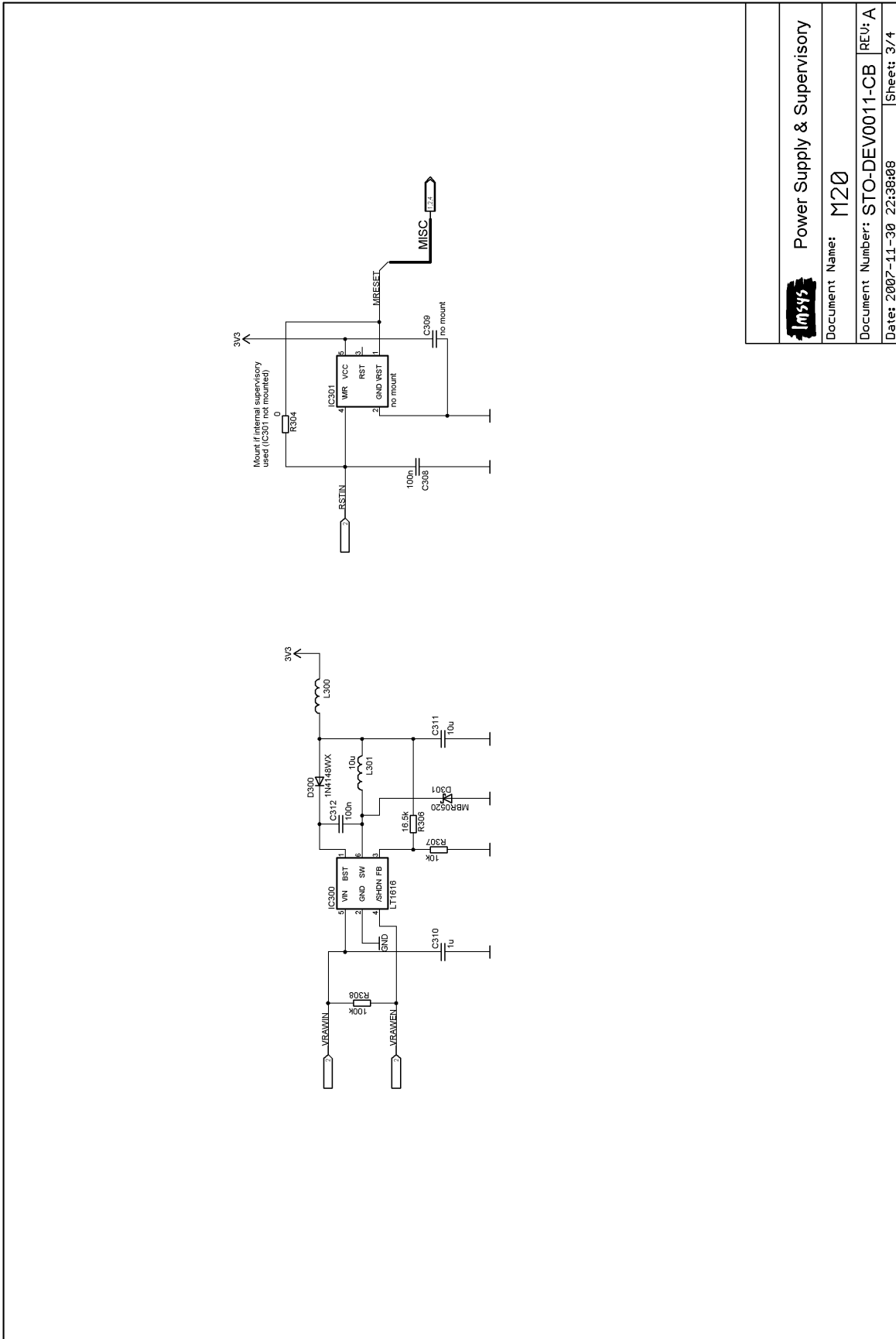
Document Name: M20


Document Number: STO-DEV0011-CB

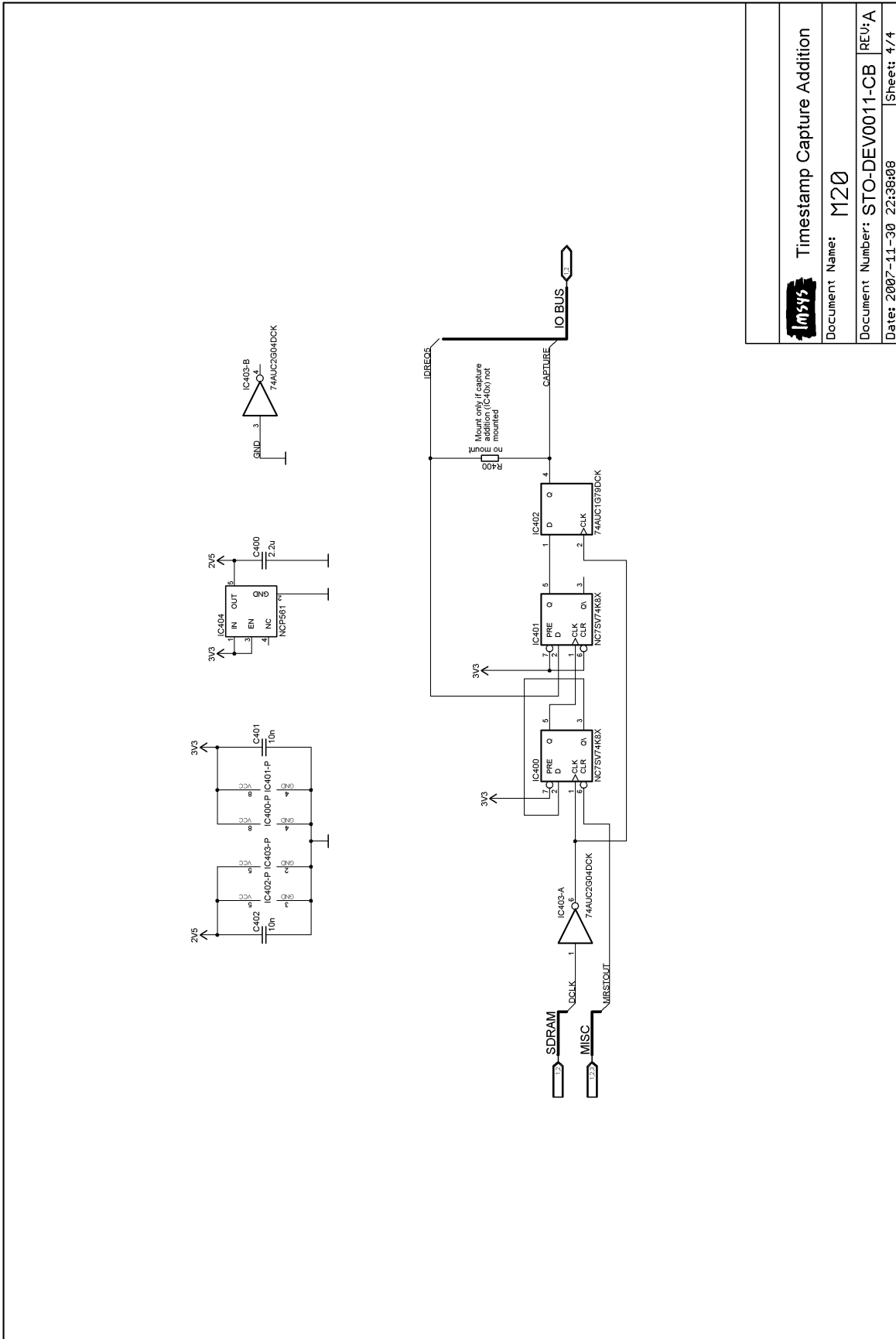
REV: A

Date: 2007-11-30 22:38:08

Sheet: 2/4



 Power Supply & Supervisory	
Document Name:	M20
Document Number:	STO-DEV0011-CB
Date:	2007-11-30 22:38:08
REU:	A
Sheet:	3/4



Timestamp Capture Addition

Document Name: M20

Document Number: STO-DEV0011-CB

REV: A

Date: 2007-11-30 22:38:08

Sheet: 4/4

Appendix B. Bill of Materials

Ref	Part number/Value	Description	Package	Mfgr
Integrated circuits (IC)				
IC100	IM3000-BA10	Microprocessor	SSBGA-180	Imsys Tech.
IC200	MT48LC16M16A2P-6:G	SDRAM 16M x 16, 167MHz	TSOP-54	Micron
IC201	AT45DB642D-CNU	Serial flash 64 Mbit	CASON	Atmel
IC300	LT1616	Switching voltage regulator	SOT23-6	Linear
IC400	NC7SV74K8X	Single D-flipflop w/preset and clear	US8	Fairchild
IC401	NC7SV74K8X	Single D-flipflop w/preset and clear	US8	Fairchild
IC402	74AUC1G79DCK	Single D-flipflop, Q output only	SC70-5	Texas Instr.
IC403	74AUC2G04DCK	Dual inverter	SC70-6	Texas Instr.
IC404	NCP561SN25T1G	LDO regulator 2.5V	SOT23-5	ON Semi.
Crystals (X)				
X100	FA-238/20MHz/18pF	Crystal, 50ppm		Epson
X101	MC-146/32768Hz/12.5pF	Crystal, 20ppm		Epson
Diodes (D,Z)				
D102	SML-LX3632SISUGSBC	RGB LED, 3.6 x 3.2 mm	6-pad	Lumex
D300	1N4148WX	Switching diode	SOD323	MCC
D301	MBR0520L	Schottky diode	SOD123	Fairchild
Resistors (R,RV)				
R101	470	Thick film resistor, 1/16W, 1%	0402	
R102	470	Thick film resistor, 1/16W, 1%	0402	
R103	47	Thick film resistor, 1/16W, 1%	0402	
R104	10k	Thick film resistor, 1/16W, 1%	0402	
R105	10k	Thick film resistor, 1/16W, 1%	0402	
R107	10k	Thick film resistor, 1/16W, 1%	0402	
R108	10k	Thick film resistor, 1/16W, 1%	0402	
R109	4.7M	Thick film resistor, 1/16W, 5%	0402	
R110	4.7M	Thick film resistor, 1/16W, 5%	0402	
R200	10k	Thick film resistor, 1/16W, 1%	0402	
R304	0	Thick film resistor, 1/16W, 1%	0402	
R306	16.5k	Thick film resistor, 1/16W, 1%	0402	
R307	10k	Thick film resistor, 1/16W, 1%	0402	
R308	100k	Thick film resistor, 1/16W, 1%	0402	

Ref	Part number/Value	Description	Package	Mfgr
Capacitors (C)				
C100	27p	Ceramic cap, NP0, 50V, 5%	0402	
C101	27p	Ceramic cap, NP0, 50V, 5%	0402	
C102	22p	Ceramic cap, NP0, 50V, 5%	0402	
C103	22p	Ceramic cap, NP0, 50V, 5%	0402	
C104	100n	Ceramic cap, X7R, 16V, 10%	0402	
C105	2200n	Ceramic cap, Y5V, 16V, -20/+80%	0603	
C106	2200n	Ceramic cap, Y5V, 16V, -20/+80%	0603	
C107	2200n	Ceramic cap, Y5V, 16V, -20/+80%	0603	
C108	10n	Ceramic cap, X7R, 50V, 10%	0402	
C109	10n	Ceramic cap, X7R, 50V, 10%	0402	
C110	10n	Ceramic cap, X7R, 50V, 10%	0402	
C111	10n	Ceramic cap, X7R, 50V, 10%	0402	
C112	10n	Ceramic cap, X7R, 50V, 10%	0402	
C113	10n	Ceramic cap, X7R, 50V, 10%	0402	
C114	10n	Ceramic cap, X7R, 50V, 10%	0402	
C200	10n	Ceramic cap, X7R, 50V, 10%	0402	
C201	10n	Ceramic cap, X7R, 50V, 10%	0402	
C202	10n	Ceramic cap, X7R, 50V, 10%	0402	
C203	10n	Ceramic cap, X7R, 50V, 10%	0402	
C204	10n	Ceramic cap, X7R, 50V, 10%	0402	
C308	100n	Ceramic cap, X7R, 16V, 10%	0402	
C310	1000n	Ceramic cap, Y5V, 16V, -20/+80%	0603	
C311	10 μ	Ceramic cap, Y5V, 6.3V, -20/+80%	0805	
C312	100n	Ceramic cap, X7R, 16V, 10%	0402	
C400	2200n	Ceramic cap, Y5V, 16V, -20/+80%	0603	
C401	10n	Ceramic cap, X7R, 50V, 10%	0402	
C402	10n	Ceramic cap, X7R, 50V, 10%	0402	
Inductors (L)				
L100	BK1005HW121-T	Ferrite bead, 120ohm/100MHz/450mA	0402	
L300	BK1005HW121-T	Ferrite bead, 120ohm/100MHz/450mA	0402	
L301	CBC3225T100MR	Power inductor 10 μ H	1210	Taiyo Yuden
Connectors (P,J)				
J200	FX10A-100S/10-SV	100 pin FX10 receptacle, w/guides		Hirose
59 components total				